

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Michael S. Leung, et al.  
Serial No. : 10/666,399  
Filed : September 18, 2003  
Examiner : Kalam, Abul  
Art Unit : 2814  
Customer No. : 23935

Title: MOLDED CHIP FABRICATION METHOD AND APPARATUS


Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**NOTIFICATION OF FILING OF DIVISIONAL APPLICATION**

Notification is hereby being made of the filing of a divisional application for the above application.

Respectfully submitted,

Dated: 9/10/10

  
Jaye G. Heybl  
Registration No. 42,661  
Attorney for Applicants

KOPPEL, PATRICK, HEYBL & DAWSON

Westlake Village, California 91361  
(805) 373-0060  
(UJGH/NotofFiling/P0298US-7)